- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Designed to Facilitate Incident-Wave Switching for Line Impedances of 25 Ω or Greater
- Distributed V_{CC} and GND Pins Minimize Noise Generated by the Simultaneous Switching of Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (JT, NT)

description

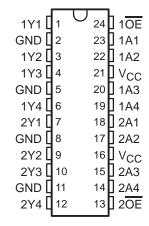
These $25-\Omega$ octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These buffers are capable of sinking 188-mA I_{OL} , which facilitates switching 25- Ω transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more reliable system operation.

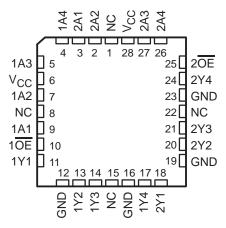
When the output-enable (1 \overline{OE} and 2 \overline{OE}) inputs are low, the device transmits data from the A inputs to the Y outputs. When 1 \overline{OE} and 2 \overline{OE} are high, the outputs are in the high-impedance state.

The SN54BCT25244 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74BCT25244 is characterized for operation from 0°C to 70°C.

SN54BCT25244 . . . JT OR W PACKAGE SN74BCT25244 . . . DW OR NT PACKAGE (TOP VIEW)



SN54BCT25244 . . . FK PACKAGE (TOP VIEW)



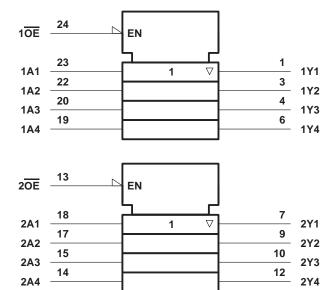
NC - No internal connection

FUNCTION TABLE (each buffer/driver)

INPU	JTS	ОИТРИТ
OE	Α	Y
L	Н	Н
L	L	L
Н	Χ	Z

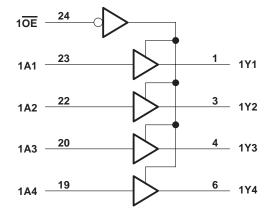


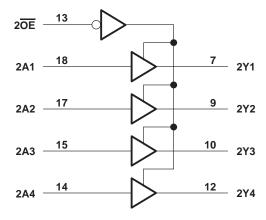
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	\ldots $-0.5\ V$ to 7 V
Input voltage range, V _I (see Note 1)	\ldots $-0.5\ V$ to 7 V
Voltage range applied to any output in the disabled or power-off state, V _O	\dots –0.5 V to 5.5 V
Voltage range applied to any output in the high state, V _O	\dots -0.5 V to V _{CC}
Input clamp current, I _{IK} (V _I < 0)	30 mA
Current into any output in the low state, I _O : SN54BCT25244	250 mA
SN74BCT25244	376 mA
Operating free-air temperature range: SN54BCT25244	-55°C to 125°C
SN74BCT25244	$\dots \dots 0^{\circ} C$ to $70^{\circ} C$
Storage temperature range	-65° C to 150° C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		SN5	SN54BCT25244		SN7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
lıK	Input clamp current			-18			-18	mA
ІОН	High-level output current			-53			-80	mA
loL	Low-level output current			125			188	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEG	TEST CONDITIONS				SN7	4BCT25	244	UNIT
PARAMETER	l les	ST CONDITIONS	MIN TYPT MAX MIN TYPT		MAX	UNIT			
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$				2.7			
VOH	V _{CC} = 4.5 V	$I_{OH} = -53 \text{ mA}$	2						V
	VCC = 4.5 V	$I_{OH} = -80 \text{ mA}$				2			
		I _{OL} = 94 mA		0.38	0.55		0.42	0.55	
V_{OL}	V _{CC} = 4.5 V	I _{OL} = 125 mA			0.8				V
		I _{OL} = 188 mA						0.7	
lį	V _{CC} = 5.5 V,	V _I = 5.5 V			0.1			0.1	mA
lН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			-0.6			-0.6	mA
I _{OZH}	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
lozL	V _{CC} = 5.5 V,	V _O = 0.5 V			-50			-50	μΑ
ICCL	$V_{CC} = 5.5 \text{ V},$	Outputs open		90	119		90	119	mA
ІССН	V _{CC} = 5.5 V,	Outputs open		59	78		59	78	mA
lccz	V _{CC} = 5.5 V,	Outputs open		7	11		7	11	mA
C _i	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		5.5			5.5		pF
Co	V _{CC} = 5 V,	V _O = 2.5 V or 0.5 V		17			17		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Note 3)

	• •		, ,		•					
PARAMETER	FROM (INPUT)	TO (OUTBUT)	TO $T_{A} = 25^{\circ}C$ SN54BCT25244 SN74BCT25244			SN54BCT25244		Γ25244	UNIT	
	(INFOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	_	V	1	3.2	4.9	1	5.6	1	5.5	no
t _{PHL}	A	Ť	2	4	5.6	2	6.3	2	6	ns
^t PZH	OE	V	3.2	5.6	8.5	3.2	9.7	3.2	9.3	no
t _{PZL}		Y	3.7	6.3	9.2	3.7	10.4	3.7	10.2	ns
^t PHZ	ŌĒ	V	1.6	3.6	5.5	1.6	6.5	1.6	6.3	200
tPLZ		Ť	3.1	5.3	7.8	3.1	9.5	3.1	8.4	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74BCT25244DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT25244DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT25244DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT25244DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT25244DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT25244DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT25244NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT25244NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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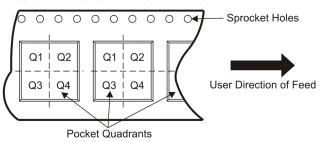
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT25244DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing Pins		SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74BCT25244DWR	SOIC	DW	24	2000	346.0	346.0	41.0	

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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